IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Priority Application Serial No
Priority Filing Date August 30, 2000
Inventor Jerome Michael Eldrigde
Assignee Micron Technology, Inc.
Priority Group Art Unit
Priority Examiner Laura M. Schillinger
Attorney's Docket No
Title: Methods for Forming Void Regions, Dielectric Regions and Capacitor Constructions

PRELIMINARY AMENDMENT

To:

Assistant Commissioner for Patents

Washington, D.C. 20231

From:

D. Brent Kenady (Tel. 509-624-4276; Fax 509-838-3424)

Wells, St. John, Roberts, Gregory & Matkin P.S.

601 W. First Avenue, Suite 1300 Spokane, WA 99201-3828

AMENDMENTS

In the Specification

At page 1, before the "Technical Field" insert the following:

CROSS REFERENCE TO RELATED APPLICATION

This patent resulted from a divisional application of U.S. Patent Application Serial No. 09/651,815, filed August 30, 2000, entitled "Methods of Forming Void Regions, Dielectric Regions and Capacitor Constructions," naming Jerome Michael Eldridge as inventor, which is a continuation of U.S. Patent Application Serial No. 09/146,117, filed September 2, 1998, now U.S. Patent No. 6,140,200, the disclosure of which is incorporated by reference.

In the Claims

Please replace the claims with the following clean version of the entire set of pending claims, in accordance with 37 C.F.R. § 1.121(c)(1)(i). Cancel all previous versions of any pending claim.

A marked up version showing amendments to any claims being changed is provided in one or more accompanying pages separate from this amendment in accordance with 37 C.F.R. § 1.121(c)(1)(ii). Any claim not accompanied by a marked up version has not been changed relative to the immediate prior version, except that marked up versions are not being supplied for any added claim or canceled claim.

CLAIMS

Cancel claims 1-89 and 97.

90. A method of forming a void region associated with a substrate, comprising:

providing a substrate;

forming a sacrificial mass over the substrate;

forming a layer over the mass; and

subjecting the mass to conditions wherein a component of the mass transports from the mass into the layer to form a mixture of the layer and the component, and wherein transporting the component leaves an enclosed void region between the substrate and the mixture of the layer and the component.

91. The method of claim 90 wherein the layer comprises silicon nitride.

92. A method of forming a void region associated with a substrate, comprising:

providing a substrate;

forming a sacrificial mass over the substrate;

forming a metal-comprising layer over the mass; and

subjecting the mass to conditions which transport a component of the mass to the metal-comprising layer, the transported component being alloyed into the metal-comprising layer and leaving a hermetically-sealed void region between the metal-comprising layer and the substrate.

- 93. The method of claim 92 wherein less than all of the sacrificial mass is transported to the metal-comprising layer.
- 94. The method of claim 92 wherein substantially all of the sacrificial mass is transported to the metal-comprising layer.
- 95. The method of claim 92 wherein the metal-comprising layer comprises one or more of vanadium, zirconium, titanium, tantalum and iron.

96. The method of claim 92 wherein the metal-comprising layer comprises one or more of titanium or tantalum, wherein the component is carbon, and wherein the component is alloyed as one or both of a metal-carbide and a solid solution.

97. Cancel.

REMARKS

Claims 1-89 and 97 have been canceled without prejudice. Claims 90-96 are pending in the application, and Applicant requests examination of such pending claims.

Respectfully submitted,

Dated: /-//-02

D. Brent Kenady Reg. No. 40,045

EL169834801

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICATION FOR LETTERS PATENT

METHODS OF FORMING VOID REGIONS, DIELECTRIC REGIONS AND CAPACITOR CONSTRUCTIONS

INVENTOR

Jerome Michael Eldridge

ATTORNEY'S DOCKET NO. MI22-978

Priority Application Serial No 09/651,815
Priority Filing Date August 30, 2000
Inventor Jerome Michael Eldridge
Assignee Micron Technology, Inc.
Priority Group Art Unit
Priority Examiner Laura M. Schillinger
Attorney's Docket No MI22-1914
Title: Methods for Forming Void Regions, Dielectric Regions and Capacitor
Constructions

VERSION WITH MARKINGS TO SHOW CHANGES MADE ACCOMPANYING PRELIMINARY AMENDMENT

In the Specification

The replacement specification paragraphs incorporate the following amendments. Underlines indicate insertions and strikeouts indicate deletions.

CROSS REFERENCE TO RELATED APPLICATION

This patent resulted from a divisional application of U.S. Patent Application Serial No. 09/651,815, filed August 30, 2000, entitled "Methods of Forming Void Regions, Dielectric Regions and Capacitor Constructions," naming Jerome Michael Eldridge as inventor, which is a continuation of U.S. Patent Application Serial No. 09/146,117, filed September 2, 1998, now U.S. Patent No. 6,140,200, the disclosure of which is incorporated by reference.

In the Claims

The claims have been amended as follows. <u>Underlines</u> indicate insertions and strikeouts indicate deletions.

Claims 1-89 and 97 have been cancelled without prejudice.

-END OF DOCUMENT-

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Priority Application Serial No 09/651,815
Priority Filing Date August 30, 2000
Inventor Jerome Michael Eldridge
Assignee Micron Technology, Inc.
Priority Group Art Unit
Priority Examiner Laura M. Schillinger
Attorney's Docket No MI22-1914
Title: Methods of Forming Void Regions, Dielectric Regions and Capacitor Constructions

INFORMATION DISCLOSURE STATEMENT

References - - See attached Form PTO-1449

In compliance with 37 C.F.R. §§ 1.56, 1.97 and 1.98, your attention is directed to the United States patents and other references listed on the attached Form PTO-1449. No admission is made regarding whether all the submitted references are prior art.

The listed references were cited by, or submitted to, the Office in the parent, copending application of the above-identified application. The above-identified application is a divisional application of co-pending Application Serial No. 09/651,815, filed August 30, 2000, upon which the above-identified application relies for a priority date under 35 U.S.C. §120. Such prior disclosure is sufficient for the above-identified application as far as copies of the references are concerned. 37 C.F.R. §1.98(d) and MPEP §609(2). As a courtesy, Applicant submits copies of the cited references for review.

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Citation of these references is respectfully requested.

Respectfully submitted,

Date: 1-11-02

D. Brent Kenady Reg. No. 40,045

Wells, St. John, Roberts, Gregory & Matkin P.S.

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	AU		M B Anand, "Use of Gas as Low-k Interlayer Dielectric in LSI's Demonstration of Feasibility", IEEE Transactions On Electron								lectron	
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

PRIORITY PATENT APPLICATION SERIAL NO	651.815
PRIORITY FILING DATE August 3	0. 2000
INVENTORSHIP Jerome Michael F	Eldridae
PRIORITY GROUP ART UNIT	. 2813
PRIORITY EXAMINER Laura M. Sc	hillinger
ATTORNEY'S DOCKET NO MIZ	22-1914
TITLE: Methods for Forming Void Regions, Dielectric Regions and Ca	
Constructions	

Assistant Commissioner for Patents Washington, D. C. 20231
Attention: Official Draftsman

SUBSTITUTE DRAWING REQUEST

Please enter the enclosed formal drawings in the above-referenced application in place of the originally filed drawings. The content of the drawings are identical to those now on file in this application.

Acknowledgment of receipt of the formal drawing sheets and their acceptance into the file is requested.

Respectfully submitted,

Date: <u>/-1/-02</u>

By:

1

D. Brent Kenady Reg. No.: 40,045

WELLS, ST. JOHN, ROBERTS, GREGORY & MATKIN P.S.

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Enclosures: 4 sheets of Formal Drawings (Figs. 1-8)